Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

## 2SK2996

# DC-DC Converter, Relay Drive and Motor Drive Applications

• Low drain–source ON resistance : RDS (ON) =  $0.74 \Omega$  (typ.) • High forward transfer admittance :  $|Y_{fs}| = 6.8 S$  (typ.)

• Low leakage current :  $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 600 \text{ V)}$ • Enhancement mode :  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA)}$ 

#### Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	600	٧	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		V <sub>DGR</sub>	600	V	
Gate-source voltage	Gate-source voltage		±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	10	А	
Diam current	Pulse (Note 1)	I <sub>DP</sub>	30		
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	45	W	
Single pulse avalanche energy (Note 2)		EAS	252	mJ	
Avalanche current		I <sub>AR</sub>	10	А	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	4.5	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C	

10±0.3

03.2±0.2

2.7±0.2

0.75±0.15

1.1

0.75±0.15

1.2 3

1. GATE
2. DRAIN
3. SOURCE

JEDEC

JEITA

SC-67

TOSHIBA

2-10R1B

Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	2.78	°C / W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 4.41 mH,  $R_{G}$  = 25  $\Omega$ ,  $I_{AR}$  = 10 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature.

This transistor is an electrostatic-sensitive device.

Please handle with caution.

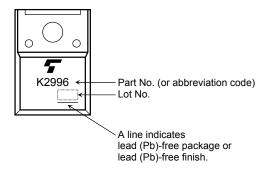
### **Electrical Characteristics (Ta = 25°C)**

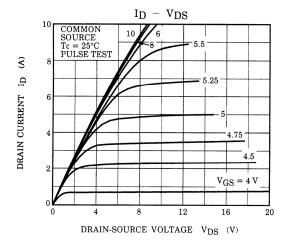
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Gate-source bro	eakdown voltage	V (BR) GSS	I <sub>G</sub> = ±10 μA, V <sub>DS</sub> = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	600	_	_	V
Gate threshold v	/oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5 A	_	0.74	1.0	Ω
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 5 A	3.4	6.8	_	S
Input capacitano	ce	C <sub>iss</sub>		_	1500	_	
Reverse transfe	r capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	13	_	pF
Output capacitance		Coss	]	_	140	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10 \text{ V}}{_{0 \text{ V}}} \prod \qquad \stackrel{I_{D} = 5 \text{ A}}{\underset{\leftarrow}{}_{1} \text{A}}$	_	15	_	
	Turn-on time	t <sub>on</sub>	$\begin{array}{c} \begin{array}{c} \begin{array}{c} \begin{array}{c} \\ \\ \\ \end{array} \end{array} \end{array} \begin{array}{c} \begin{array}{c} \\ \\ \\ \end{array} \end{array} \begin{array}{c} \\ \\ \end{array} \begin{array}$	_	55	ı	ns
	Fall time	t <sub>f</sub>		_	27	1	115
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm W} = 10 \mu \rm s$	_	145	ı	
Total gate charge (gate-source plus gate-drain)		Qg			38		
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$		21	_	nC
Gate-drain ("miller") charge		$Q_{gd}$		_	17	_	

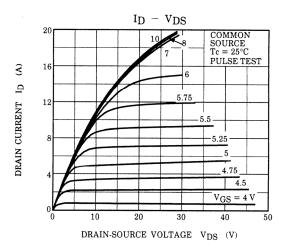
## Source-Drain Ratings and Characteristics (Ta = 25°C)

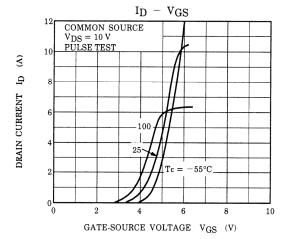
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	-	_	_	10	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	-	_	_	30	А
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 10 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 10 A, V <sub>GS</sub> = 0 V		1600	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 100 A / μs	_	17	_	μC

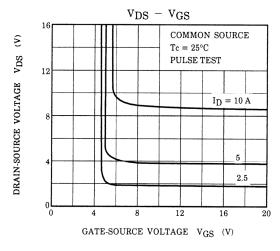
### Marking

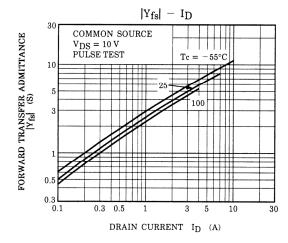


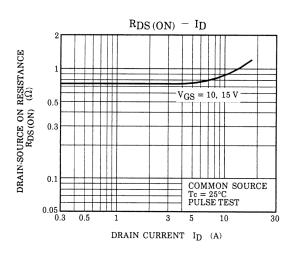


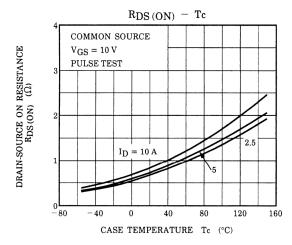


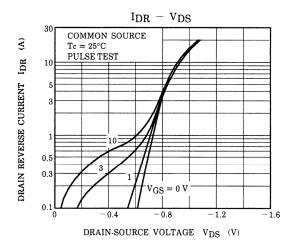


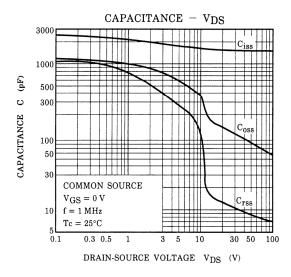


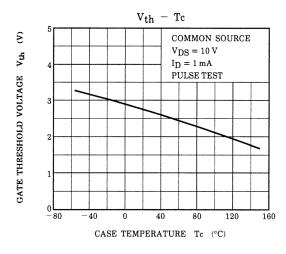


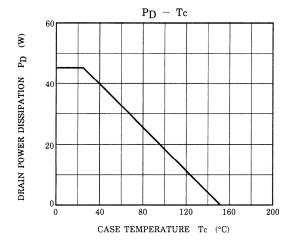


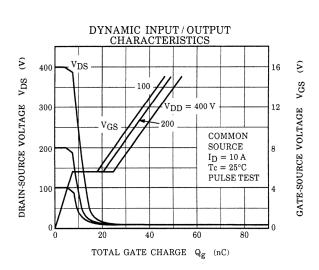


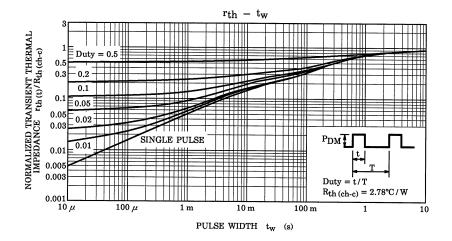


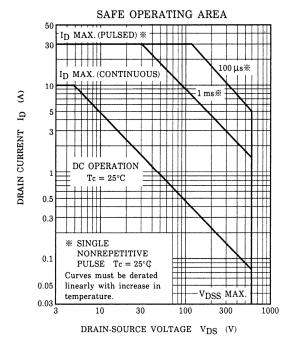


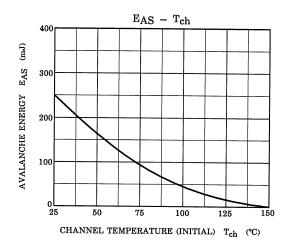


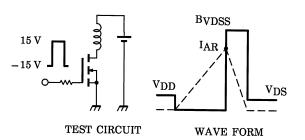












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 4.41~mH \end{aligned} \qquad E_{AS} &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right) \end{aligned}$$

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20070701-EN

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